



# ORDER FORM FOR MUMPS MANUFACTURING

CMP RUN:

TOPCELL NAME<sup>(1)</sup>:

PROCESS:

## DELIVERY & INVOICING

CIRCUIT'S PURPOSE:  Education  Research  Industry

INSTITUTION/COMPANY:

DELIVERY TO: Name:

Phone:

Institution/company:

Full address (no PO box):

SPECIAL REQUEST ON DELIVERY:  yes  no

*If no, circuits will be sent by courier service (UPS) with our standard 'invoice for customs' for foreign countries.*

INVOICE TO: Name:

Phone:

E-mail:

Institution/Company:

VAT id:

Address:

(Europe only)

P.O. number:

CIRCUIT SIZE: DeltaX =  µm

DeltaY =  µm

NUMBER OF PARTS<sup>(2)</sup> Bare dies:  Packaged:

PACKAGE:

SUB-DICING<sup>(3)</sup>:  yes  no number:

HF REALEASE<sup>(4)</sup>:  yes  no number:

SUPER-CRITICAL CO<sup>2</sup> DRYING<sup>(4)</sup>:  yes  no number:

COLOUR PLOTS:  yes  no number:

ADDITIONAL SERVICES<sup>(5)</sup>:

### Reserved to CMP

area:

price

price

set\_up

price:

price

price

price

price

shipment:

**Total:**

*By signing the present order form, the responsible person accepts the Terms and Conditions that are in <http://cmp.imag.fr/services/terms-and-conditions.html>*

**Name and signature of the responsible person:**

Name:

date:

signature:



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## TECHNICAL INFORMATION

TECHNICAL ENQUIRIES<sup>67</sup>): Name:

Phone:

E-mail:

CIRCUIT TRANSFER:  web account (default)  ftp (files > 20MB)

DESCRIPTION FORMAT<sup>(7)</sup>:  GDSII Other:

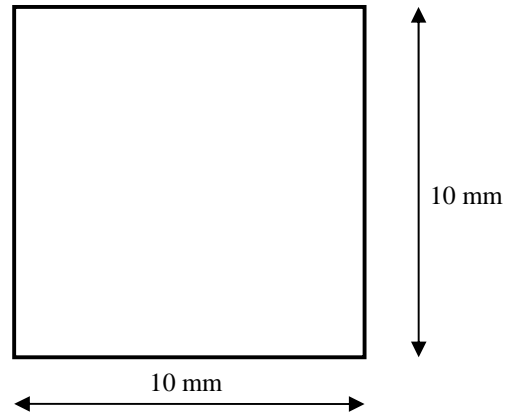
CAD TOOL: version:

DESIGN KIT: version:

DID YOU USE GENERATORS ?  yes  no

DRC VIOLATIONS:  yes  no *If you request DRC violations, please make a case overleaf.*

### **SUB-DICING DIAGRAM<sup>(2)</sup>** (if required)



LOW VOLUME PRODUCTION EXPECTED?  yes  perhaps  no

VERSION OF DESIGN THAT SHOULD BE PRODUCED:  this one after test  an improved one

START PRODUCTION:  in next 6 months  < 1 year  > 1 year

EXPECTED NUMBER OF CIRCUITS:  < 100  < 1000  < 10000  > 10000

**CIRCUIT FUNCTION** *(a few lines in English. Mandatory for non E.U. countries, used for export regulation. Will be published in the CMP annual report)*



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**DO NOT SEND THIS PAGE**

### **RESERVATION REQUESTS**

For technologies of STmicroelectronics you must send a reservation request **one month before the deadline**. Please contact us by Email for the document.

### **PACKAGES**

Packaging service is available if you are following packaging rules of CMP. Prices, list of packages and cavity maps are in:

<http://cmp.imag.fr> -> Technologies -> Packaging

<http://cmp.imag.fr> -> Technologies -> Price list -> CMP price list (right column)

Contact us for unlisted ceramic packages, we will check with our subcontractors.

Contact us for plastic packages. Small sets of plastic packages are possible. Main packages are SOIC, SSOP, LPCC (leadless), QFP, PLCC and EDQUAD (thermal solution).

**NB:** Design your pad ring according to the chosen package. Long wires and big angles are accepted for prototypes in ceramic packages and in open cavity packages but they are decreasing circuit performances. Packaging rules for plastic are strict for wire length and for angles of wires.

### **NOTES**

- (1) Maximum 14 characters, the first character must be a letter.
- (2) 15 bare dies are fabricated. Sub-dicing, HF release and Super-critical CO<sup>2</sup> drying are charged.
- (3) If requested, make a sub-dicing diagram page 2. Write the number of macro-dice that must be sawed. Minimum sub-dice size: 5mm x 5mm if HF release is ordered, 2mm x 2mm if no HF.
- (4) Only for polyMUMPS. Charged by batches of 15 dies. For example a lot of 16 dies costs 2 batches like a lot of 30 dies.
- (5) If you need any other service, contact to check if we can provide it.
- (6) The person given on the form under the heading "TECHNICAL ENQUIRIES" must be rapidly available for questions and corrections of the design. The designer is generally the best choice.
- (7) For other format than gds2 contact CMP for an authorization.